MSKSEMI 美森科













ESD

TVS

TSS

MOV

GDT

PIFD

BAT54/A/C/S-7-MS

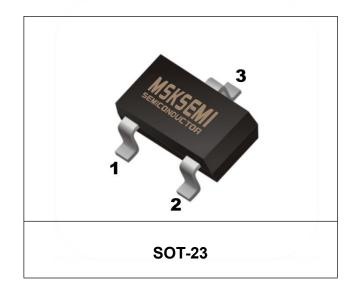
Product specification



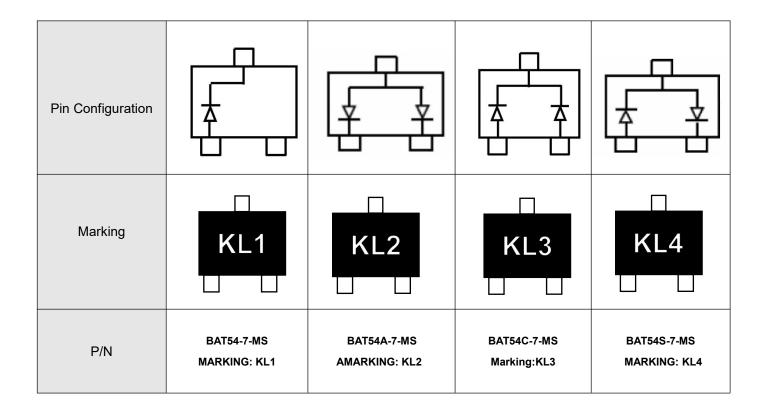


Features

Extremely Fast Switching Speed



Reference News





MAXIMUM RATINGS@Ta=25℃

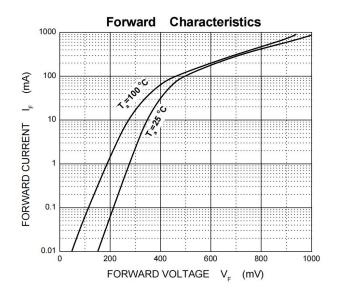
Parameter	Symbol	Limits	Unit
D. I. D. W. D. I.	V _{RRM}		
Peak Repetitive Peak reverse voltage Working Peak Reverse Voltage	V_{RWM}	30	v
	VR		
Forward Continuous Current	I _{FM}	200	mA
Power Dissipation	P _D	200	mW
Storage temperature	T _{STG}	-55- 150	℃

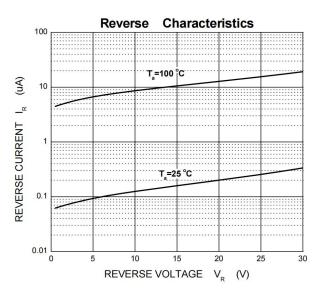
$\textbf{ELECTRICALCHARACTERISTICS} (Ta=25\,^{\circ}\text{C unless otherwise specified})$

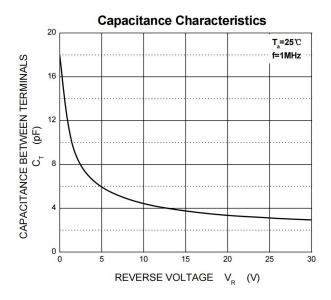
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Reverse Breakdown Voltage	V _{(BR)R}	30			٧	IR=100μA
Forward voltage	V _{F1}			0.24	٧	I _F =0. 1mA
	V _{F2}			0.32	٧	I _F =1mA
	V _{F3}			0.40	٧	I _F =10mA
	V _{F4}			0.50	٧	I⊧=30mA
	V _{F5}			1	٧	I _F =100mA
Reverse current	I _R			2	μΑ	V _R =25V
Diode Capacitance	D			10	F	V _R =1V,f=1MHz
						I _F =I _R =10mA
Reverse Recovery Time	t _{rr}			5	nS	Irr=0. $1XI_R$, $R_L=100\Omega$

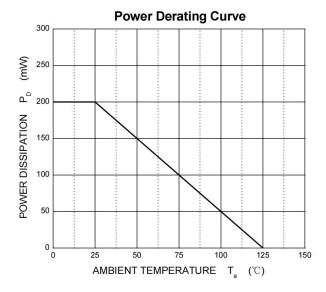


Typical Characteristics







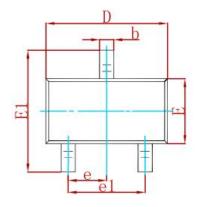


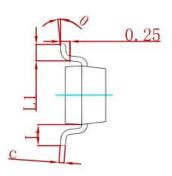


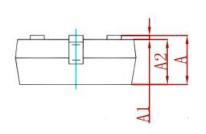




PACKAGE MECHANICAL DATA

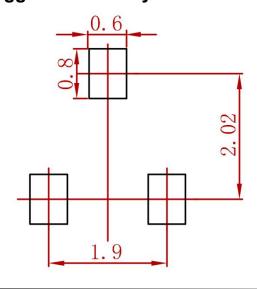






Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950) TYP	0.03	7 TYP	
e1	1.800	2.000	0.071	0.079	
L	0.550) REF	0.022	2 REF	
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
BAT54/A/C/S-7-MS	SOT-23	3000



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